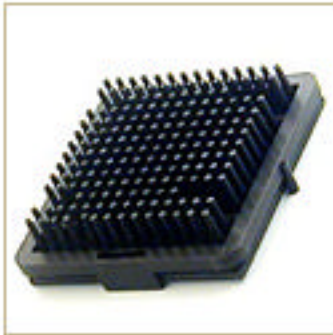




BGA Snap-on Heatsinks

EMULATION TECHNOLOGY, INC.

World Leader in Adapters, Clips, and Test Accessories



Standard BGA product provided as:

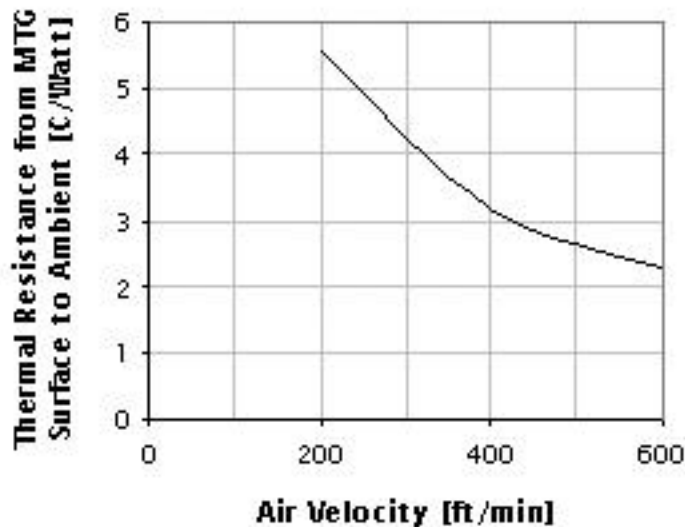
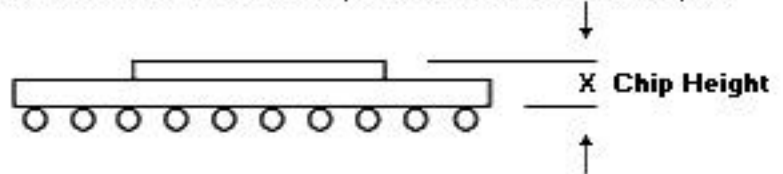
- Black anodized
- Pre-assembled as shown
- Customs available upon request

Other BGA products available:

- Rework Stencils
- Reballing Preforms
- Sockets
- Ultra-mini Pogo Pins

ET Part Number	Part Marking	Chip Pkg. Size (sq)	Heatsink Height	Fits Chip Height [x]
H-4253-09-9020-05-A	HS2166DCAB	42.5 mm	0.3 in (7.62 mm)	3.105 (+/- 0.285) mm
H-4253-10-9020-05-A	HS2167DCAB	42.5 mm	0.3 in (7.62 mm)	2.605 (+/- 0.285) mm

* Max dimensions include allowance for .005" thick thermal pad



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— HS2166DCAB - - - HS2167DCAB